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See also Skateboarding Skateboard Hardboard Rollerblading Street skating Street fashion Roller derby Ride (skateboard) References External links Category:Roller skating Category:Board sports Category:Roller skating elements1. Field of the

Invention The present invention relates to a semiconductor chip package, and more particularly, to a semiconductor chip package capable of preventing a collapse of a semiconductor chip. 2. Description of the Prior Art In the semiconductor industry, the development of multi-functional, miniature, light, thin, and high performance electronic products has driven the development of semiconductor packaging technology towards advanced high performance, miniaturization, and high reliability. For an electronic product to be miniaturized and light, and yet to maintain better performance, a highly integrated and miniaturized package structure is one way to implement the progress of the semiconductor industry. The semiconductor packaging technology is regarded as one of the most important technologies for fabricating the highly integrated and miniaturized electronic products. Please refer to FIG. 1 to FIG. 8. FIG. 1 to FIG. 8 are schematic diagrams illustrating a prior art semiconductor chip package 100. As shown in FIG. 1, a prior art semiconductor chip package 100 comprises a substrate 110, a semiconductor chip 120, a plurality of conductive wires 130, and a plurality of molding compounds 140. The molding compounds 140 encapsulates the semiconductor chip 120 and the conductive wires 130. An upper surface 111 of the substrate 110 is formed with a plurality of via holes 112 exposing the conductive wires 130. The via holes 112 connect the conductive wires 130 to the conductive lines (not shown in the figure) formed on the substrate 110. Please refer to FIG. 2 to FIG. 8. FIG. 2 to FIG. 8 are schematic diagrams illustrating the steps of manufacturing the prior art semiconductor chip package 100. As shown in FIG. 2, the substrate 110 is first prepared. Then, a plurality of conductive wires 130 is formed by a well-known method such as bonding. Next, a semiconductor chip 120 is bonded onto a surface of the substrate 110 where a plurality of conductive lines are formed. The semiconductor chip 120 is electrically connected to the conductive lines by a plurality of bonding pads 122. Then, the conductive wires 130 are encapsulated by a plurality of molding compounds 140 formed by a f678ea9f9e

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